Features

- ESD Protect for 4 high-speed I/O channels with Bi-directional
- Provide ESD protection for each line to
  IEC 61000-4-2 (ESD) ±15kV (air), ±15kV (contact)
  IEC 61000-4-4 (EFT) 40A (5/50ns)
  IEC 61000-4-5 (Lightning) 5A (8/20μs)
- **For operating voltage of 5V and below**
- **Ultra low capacitance : 0.40pF typical**
- Fast turn-on and Low clamping voltage
- Array of ESD rated diodes with internal equivalent TVS (Transient Voltage Suppression) diode
- Simplified layout for high-speed differential signaling channels
- Solid-state silicon-avalanche and active circuit triggering technology
- ***Green part***

Applications

- **USB Type-C (D+/D- with Audio signal)**
- **High Definition Multi-Media Interface (HDMI) 1.3 & 1.4 and 2.0 version**
- **DisplayPort interface**
- **SATA and eSATA interface**
- **V-By-One**
- **LVDS interfaces**
- IEEE 1394 up to 3.2 Gb/s
- Ethernet port: 10/100/1000 Mb/s
- Desktop and Notebooks PCs
- Consumer Electronics
- Set Top Box
- DVDRW Players
- Graphics Cards

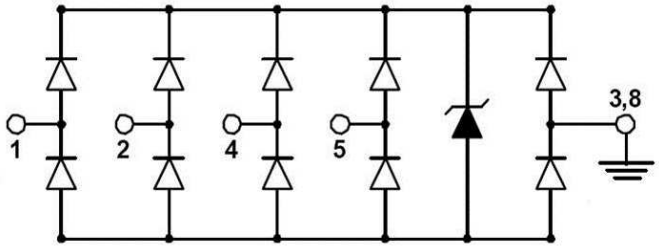
Description

AZ5425-04F is a design which includes bi-directional ESD rated diode arrays to protect high speed data interfaces. The AZ5425-04F has been specifically designed to protect sensitive components which are connected to data and transmission lines from over-voltage caused by Electrostatic Discharging (ESD), Electrical Fast Transients (EFT), Lightning, and Cable Discharge Event (CDE).

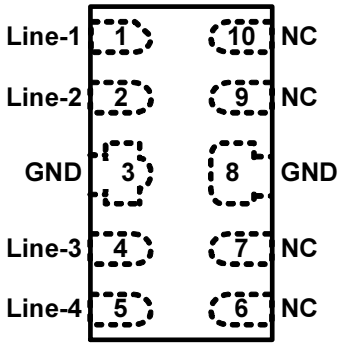
AZ5425-04F is a unique design which includes ESD rated, ultra low capacitance steering diodes and a unique design of clamping cell which is an equivalent TVS diode in a single package. During transient conditions, the steering diodes direct the transient to either the internal ESD line or to ground line. The internal unique design of clamping cell prevents over-voltage on the internal ESD line and on the I/O line, which is protecting any downstream components.

AZ5425-04F may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (±15kV air, ±8kV contact discharge).

Circuit Diagram



Pin Configuration



DFN2510P10E (Top View)

 ©2015-2016 Amazing Micro.

SPECIFICATIONS

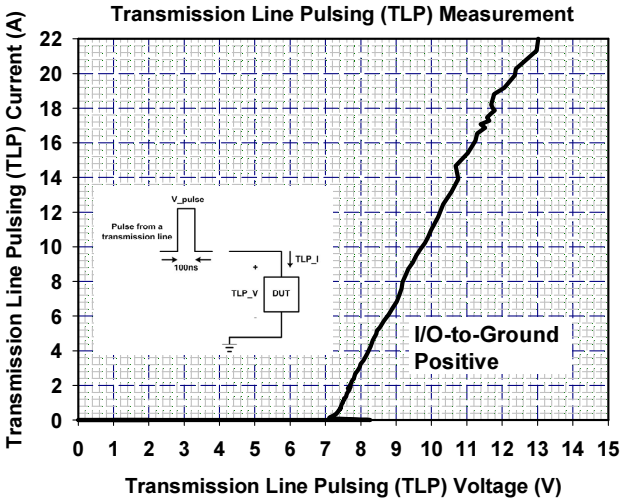
ABSOLUTE MAXIMUM RATINGS			
PARAMETER	**SYMBOL**	**RATING**	**UNITS**
Peak Pulse Current (tp= 8/20μs)	I_{PP}	±5	**A**
Operating Voltage (I/O pin-GND)	V_{DC}	±5.5	**V**
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	±15 ±15	**kV**
Lead Soldering Temperature	T_{SOL}	260 (10 sec.)	**°C**
Operating Temperature	T_{OP}	-55 to +85	**°C**
Storage Temperature	T_{STO}	-55 to +150	**°C**

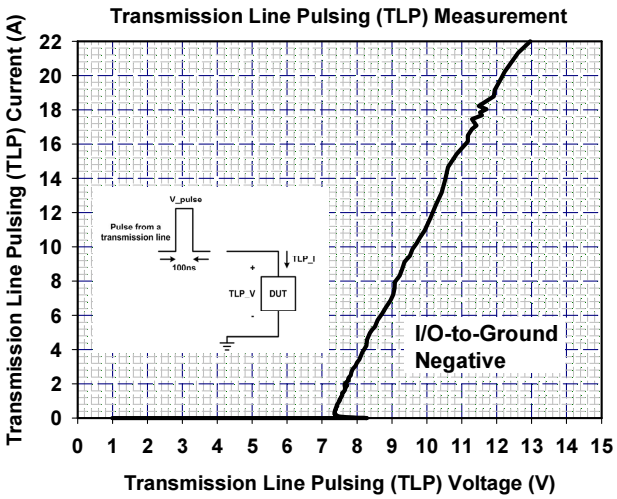
ELECTRICAL CHARACTERISTICS						
PARAMETER	**SYMBOL**	**CONDITIONS**	**MIN**	**TYP**	**MAX**	**UNITS**
Reverse Stand-Off Voltage	V_{RWM}	Pin-1,-2,-4,-5 to pin-3,-8, T=25 °C	-5		5	**V**
Channel Leakage Current	$I_{CH-Leak}$	$V_{Pin-1,-2,-4,-5}$ = ±5V, $V_{Pin-3,-8}$ = 0V, T=25 °C			1.0	**μA**
Reverse Breakdown Voltage	V_{BV}	I_{BV} = ±1mA, T=25 °C, pin-1,-2,-4,-5 to pin-3,-8	5.8		9	**V**
ESD Clamping Voltage (Note 1)	V_{clamp}	IEC 61000-4-2 +8kV (I_{TLP} = 16A), T=25 °C, Contact mode, any I/O pin to Ground		11		**V**
ESD Dynamic Turn-on Resistance	$R_{dynamic}$	IEC 61000-4-2, 0~+8kV, T=25 °C, Contact mode, any I/O pin to Ground		0.26		Ω
Channel Input Capacitance	C_{IN}	$V_{pin-3,-8}$ = 0V, V_{IN} = 0V, f = 1MHz, T=25 °C, any I/O pin to Ground		0.40	0.55	**pF**

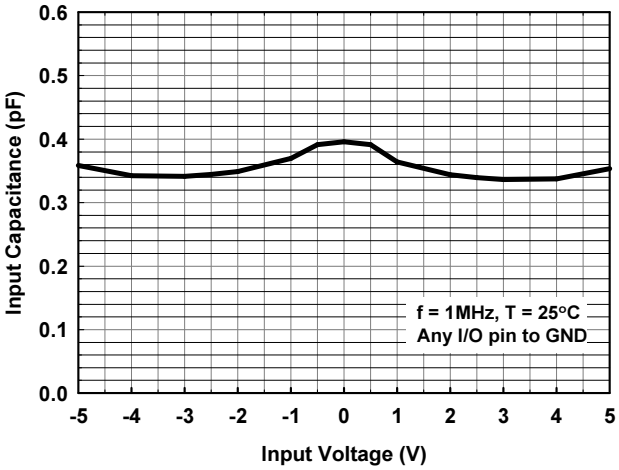
Note 1: ESD Clamping Voltage was measured by Transmission Line Pulsing (TLP) System.
TLP conditions: Z_0= 50Ω, t_p= 100ns, t_r= 1ns.

 ©2015-2016 Amazing Micro.

Typical Characteristics







 ©2015-2016 Amazing Micro.

Applications Information

The AZ5425-04F is designed to protect four data lines from transient over-voltage (such as ESD stress pulse). It provides bi-directional protection.

The device connection of AZ5425-04F is shown in the Fig. 1. In Fig. 1, the four protected data lines are connected to the ESD protection pins (pin1, pin2, pin4, and pin5) of AZ5425-04F. The ground pins (pin3 and pin8) of AZ5425-04F are the negative reference pins. These pins should be directly connected to the GND rail of PCB (Printed Circuit Board). To get minimum parasitic inductance, the path length should keep as short as possible.

AZ5425-04F can provide ESD protection for 4 I/O signal lines simultaneously. If the number of I/O signal lines is less than 4, the unused I/O pins can be simply left as NC pins.

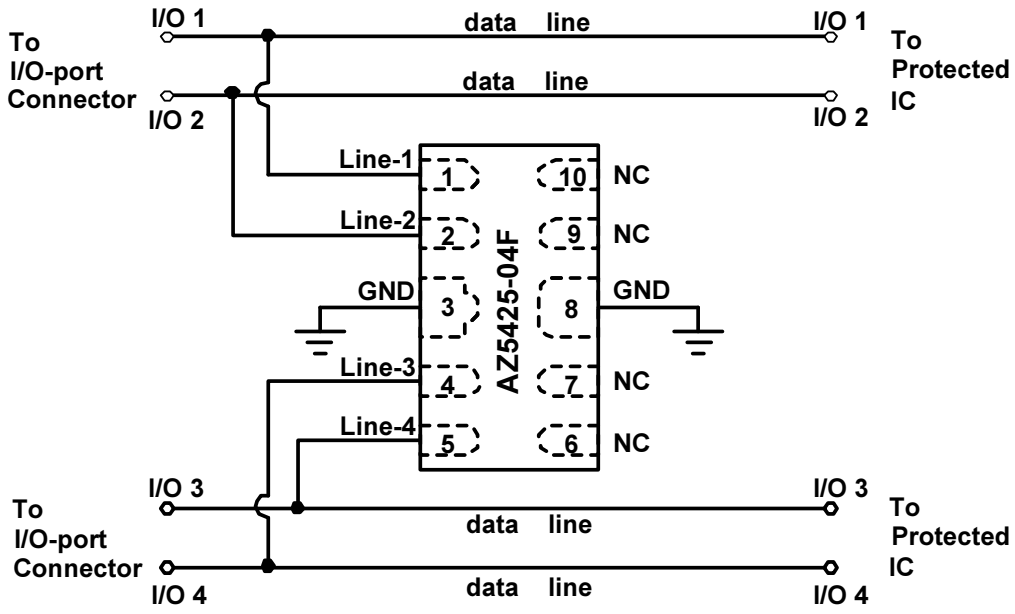


Fig. 1 Data lines connection of AZ5425-04F.

Application

AZ5425-04F is designed for protecting high speed I/O ports from over-voltage caused by Electrostatic Discharging (ESD). Thus, a lot of kinds of high speed I/O ports can be the applications of AZ5425-04F, especially, the USB Type-C port.

USB Type-C Protection for High and Low Speed Signals

For USB Type-C application, specialized analog audio devices can be connected to the USB Type-C jack via a USB Type-C connector. When Audio accessory mode is enabled, audio signal on USB Type-C connector will have negative voltage and will require bi-directional ESD rated diode arrays to protect high speed data interfaces.

ESD protection devices have an inherent junction capacitance. Even a small amount of added capacitance on a USB Type-C port will cause the impedance of the differential pair to drop. The AZ5425-04F presents **0.40pF** capacitance to each differential signal while being rated to handle >8kV ESD contact discharges (>15kV air discharge) as outlined in IEC 61000-4-2. Figure 2 shows how to

implement the AZ5425-04F in a USB Type-C application.

The AZ5425-04F is designed for allowing the traces to run straight through the device to simplify the PCB layout. As shown in Figure 2, the best way to design the PCB trace is using the flow through layout. The solid line represents the PCB trace. Note that the PCB traces are used to connect the pin pairs for each line (pin 1 to pin 10, pin 2 to pin 9, pin 4 to pin 7, pin 5 to pin 6). For example, PCB trace enters at pin 1 and exits at Pin 10 and the PCB trace connects pin 1 and 10 together. Lines 2, 3, and 4 have the same way of connection. The ground pins (pin3 and pin8) of AZ5425-04F are the negative reference pins. These pins should be directly connected to the GND plane of PCB. To get minimum parasitic inductance, the path length should keep as short as possible.

In Figure 2, the Super Speed Differential Signals, TX1+/TX1-, RX1+/RX1-, TX2+/TX2-, and RX2+/RX2-, can be protected with another low clamping voltage part for better ESD protection, e.g., AZ1143-04F. In addition, the USB voltage bus (VBUS) can be protected with single channel part, e.g., AZ5825-01F.

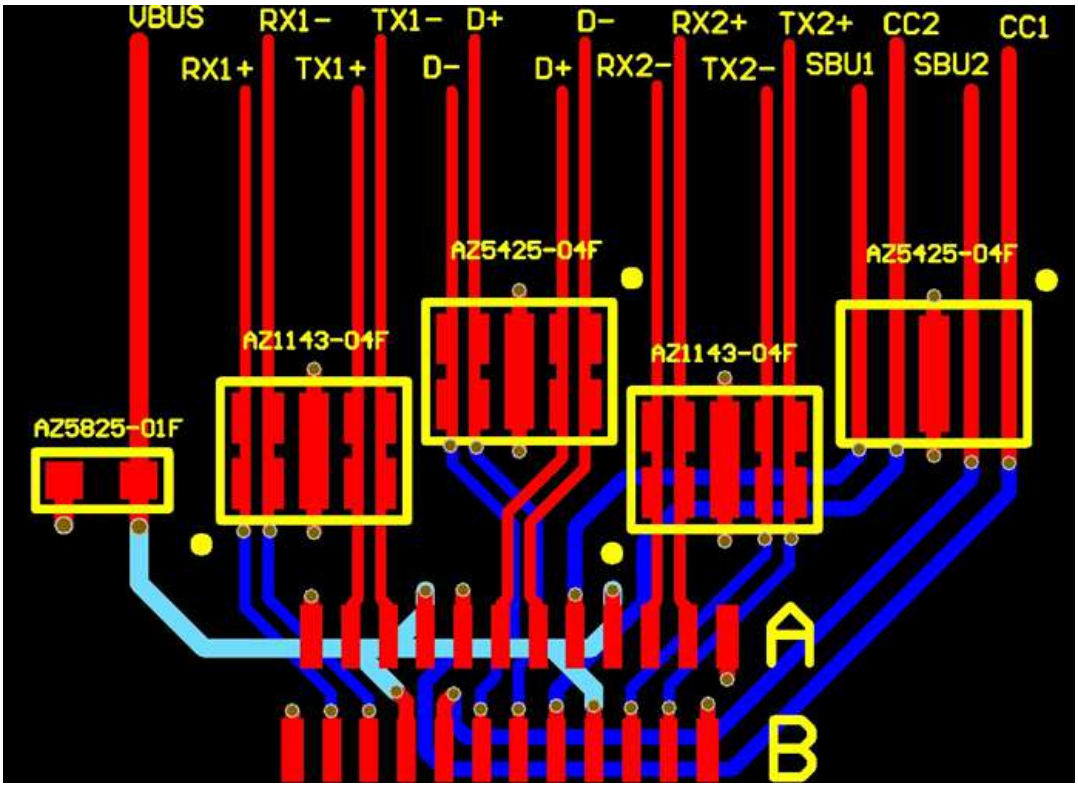
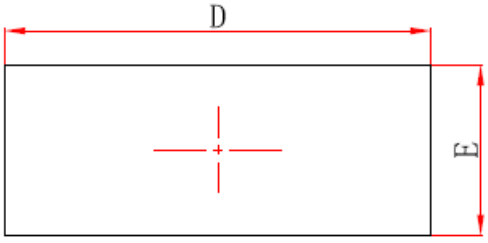


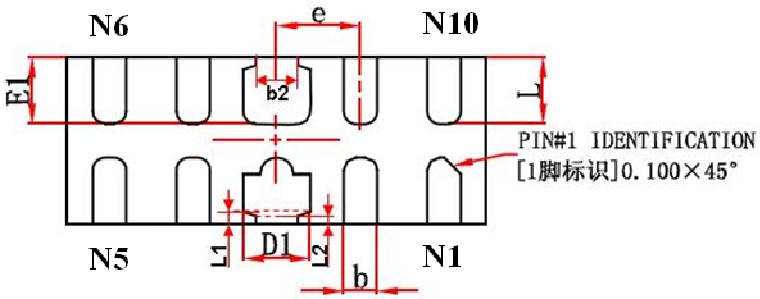
Fig. 2 USB Type-C Protection for High and Low speed signals.

 ©2015-2016 Amazing Micro.

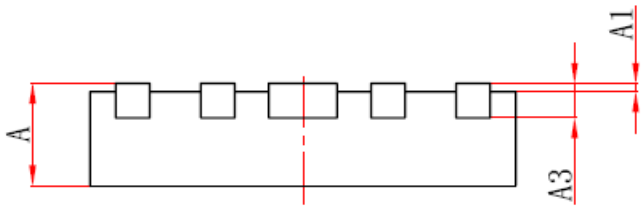
PACKAGE OUTLINE (DFN2510P10E)



TOP VIEW (unit in mm)



BOTTOM VIEW (unit in mm)

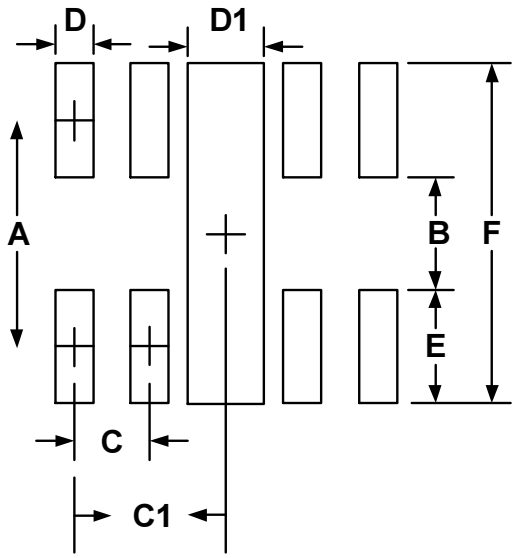


SIDE VIEW (unit in mm)

Symbol	Millimeters		Inches	
	min	max	min	max
A	0.40	0.55	0.016	0.022
A1	0.00	0.05	0.000	0.002
A3	0.152REF.		0.006 BSC	
D	2.45	2.55	0.096	0.100
E	0.95	1.05	0.037	0.041
D1	0.35	0.45	0.014	0.018
E1	0.35	0.45	0.014	0.018
b	0.15	0.25	0.006	0.010
e	0.5 BSC		0.019 BSC	
L1	0.075 REF		0.0029 REF	
L2	0.05 REF		0.0019 REF	
b2	0.20	0.30	0.0079	0.012
L	0.35	0.45	0.014	0.018

 ©2015-2016 Amazing Micro.

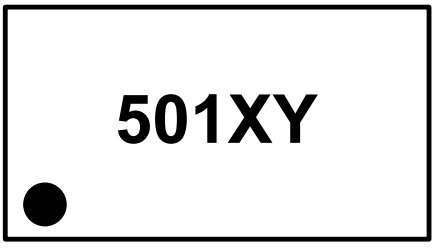
LAND LAYOUT



Dimensions		
Index	**Millimeter**	**Inches**
A	0.875	0.034
B	0.20	0.008
C	0.50	0.02
C1	1.00	0.039
D	0.25	0.01
D1	0.4	0.016
E	0.675	0.027
F	1.55	0.061

Notes:
This LAND LAYOUT is for reference purposes only. Please consult your manufacturing partners to ensure your company's PCB design guidelines are met.

MARKING CODE



501 = Device Code
X = Date Code
Y= Control Code

Part Number	Marking Code
AZ5425-04F (Green part)	**501XY**

Note. Green means Pb-free, RoHS, and Halogen free compliant.

Ordering Information

PN#	Material	Type	Reel size	MOQ/internal box	MOQ/carton
AZ5425-04F.R7G	Green	T/R	7 inch	4 reel= 12,000/box	6 box =72,000/carton

 ©2015-2016 Amazing Micro.

Revision History

Revision	Modification Description
Revision 2015/01/15	Preliminary Release.
Revision 2015/11/26	Formal Release.